

10 9 8 7 6 5 4 3 2 1

F

E

D

C

B

A

F

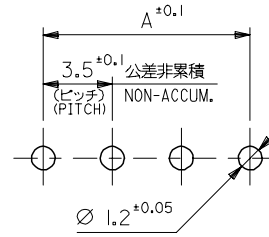
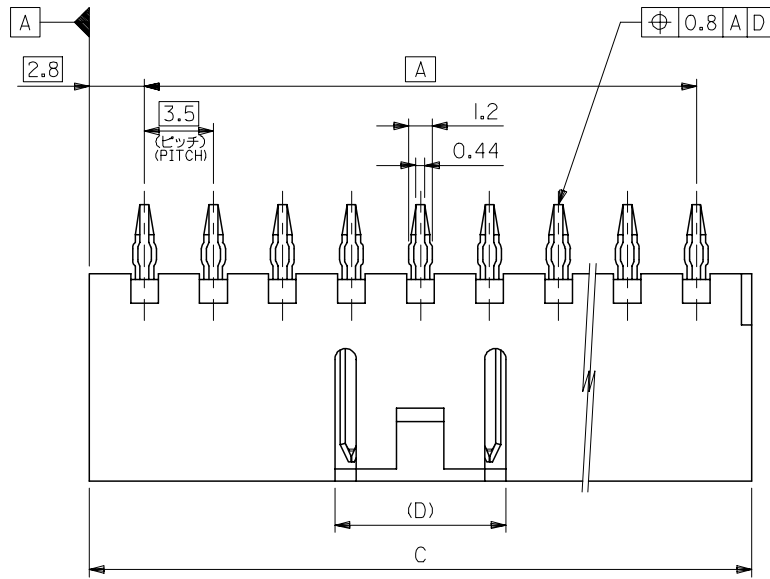
E

D

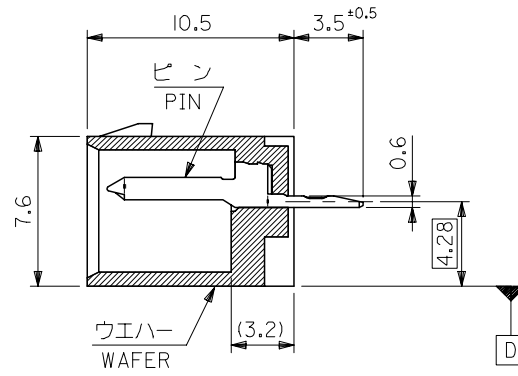
C

B

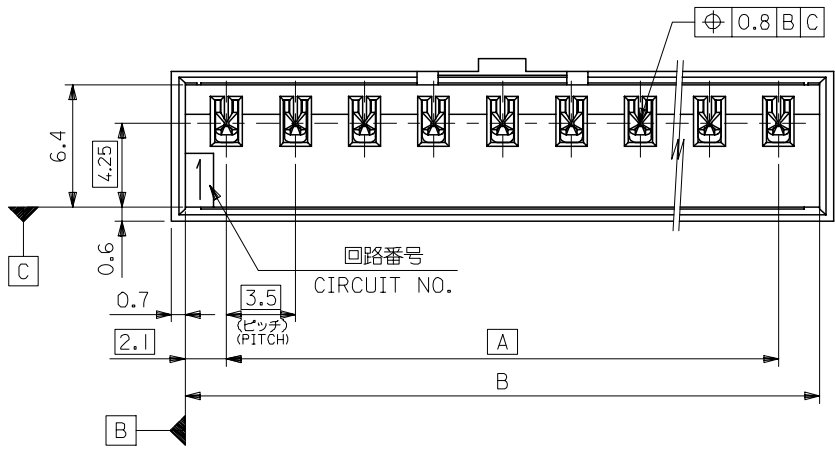
A



基板取付穴推奨寸法 (参考) (t=1.6)
RECOMMENDED P.C. BOARD HOLE DIM. (REF.)



8.7	54.6	53.2	49.0	53258-1520	15
				-1510	
	51.1	49.7	45.5	-1420	14
				-1410	
	47.6	46.2	42.0	-1320	13
				-1310	
	44.1	42.7	38.5	-1220	12
				-1210	
	40.6	39.2	35.0	-1120	11
				-1110	
	37.1	35.7	31.5	-1020	10
				-1010	
	33.6	32.2	28.0	-0920	9
				-0910	
	30.1	28.7	24.5	-0820	8
				-0810	
	26.6	25.2	21.0	-0720	7
				-0710	
	23.1	21.7	17.5	-0620	6
				-0610	
	19.6	18.2	14.0	-0520	5
				-0510	
8.7	16.1	14.7	10.5	-0420	4
				-0410	
6.1	12.6	11.2	7.0	-0320	3
				-0310	
6.1	9.1	7.7	3.5	-0220	2
				-0210	
(D)	C	B	A	53258-0210	極数
				ENG. NO.	CKT. 極数



注記
NOTES

1. 嵌合相手：51067 シリーズ
MATE WITH : 51067 SERIES
2. 材質
MATERIAL
ウエハー：PBTP (ガラス15%入り)、UL94V-0
WAFER : PBTP (G.F 15%), UL94V-0
ピン : 53258-**10 [リン青銅、銅下地、半田メッキ (t=0.254)]
PIN : [PHOS. BRO., TIN-LEAD(9:I) OVER COPPER PLATING (t=0.254)]
53258-**20 [黄銅、銅下地、半田メッキ (t=0.254)]
[BRASS, TIN-LEAD(9:I) OVER COPPER PLATING (t=0.254)]

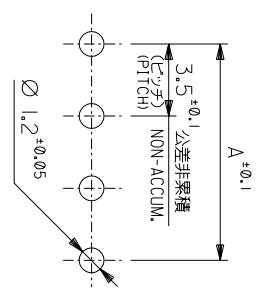
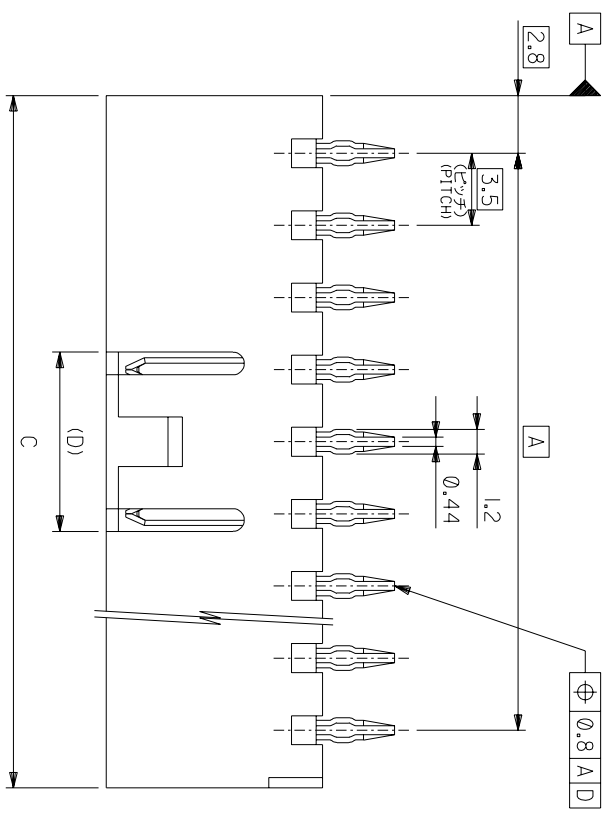
REVISED
EC No: J2005-2057
DRAWN: HOSOKAWA 2005/01/19
CHKD: TANAKA 2005/01/20
APP: NUKITA 2005/01/26

GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

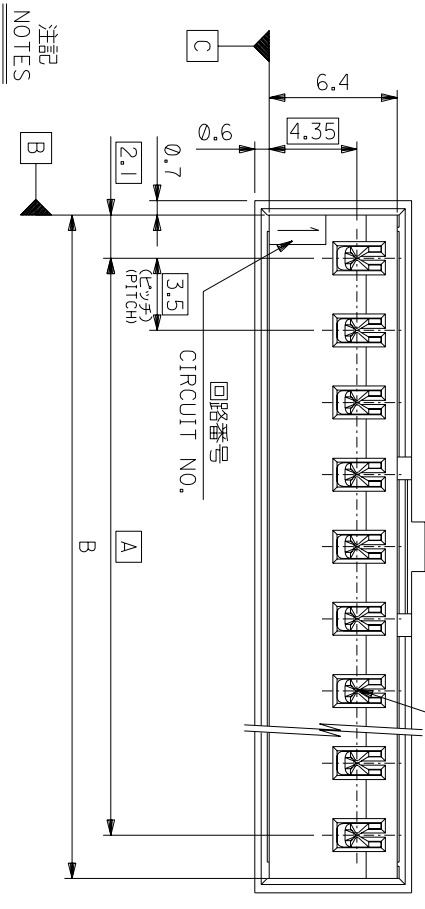
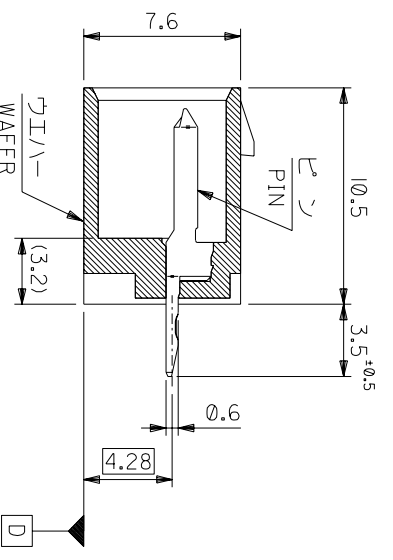
DIMENSION STYLE MM ONLY	
DRAWN BY K. ASAKAWA	DATE '89/10/13
CHECKED BY H. HIRAMOTO	DATE '93/6/29
APPROVED BY M. FUKUSHIMA	DATE '93/6/29
MATERIAL NO. SEE CHART	
SIZE A3	

SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
TITLE 3.5 W/B CONN WAFER ASSY (ST)		
MOLEX INCORPORATED		
DOCUMENT NO. SD-53258-***0	SHEET NO. 1 OF 1	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

8 7 6 5 4 3 2 1



基板取付穴推奨寸法 (参考) (t=1.0)
RECOMMENDED P.C. BOARD HOLE DIM. (REF.)



注記
NOTES

1. 嵌合相手：51067 シューズ
MATE WITH：51067 SERIES
2. 材質
MATERIAL

ワエハー：PBT/P (ガラス15%入り)、UL94V-0
WAFER：PBT/P (GF 15%, UL94V-0)
ピン：
：53258-***10 [1] 青銅、銅下地、半田メッキ (t=0.254)
：PHOS. BRO., TIN-LEAD(9:1) OVER COPPER PLATING (t=0.254)
53258-***20 [黄銅、銅下地、半田メッキ (t=0.254)
] [BRASS, TIN-LEAD(9:1) OVER COPPER PLATING (t=0.254)]

Pin No.	Dimension (D)	Dimension C	Dimension B	Dimension A	ENG. NO.	CKT. 種数
1	8.7	54.6	53.2	49.0	53258-1520	15
2					-1510	
3					-1420	
4					-1410	
5	5.1	49.7	45.5		-1320	14
6					-1310	
7	47.6	46.2	42.0		-1220	13
8					-1210	
9					-1120	
10					-1110	
11					-1020	
12					-1010	
13					-0920	
14					-0910	
15					-0820	
					-0810	
					-0720	
					-0710	
					-0620	
					-0610	
					-0520	
					-0510	
					-0420	
					-0410	
					-0320	
					-0310	
					-0220	
					-0210	

角度 ANGLE	±3°																		
30°以上	0.3																		
10°以下	0.25																		
10°以下	0.2																		
GENERAL TO FRANCES	10.2																		
材料 MATERIAL																			
注記参照 SEE NOTES																			
D	変更 (12004-4264)	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15
C	変更 (130648)	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15
B	変更 (110934)	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15
A	変更 (100265)	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15	4/15
REVISION ONLY ON CAD SYSTEM	REVISION RECORD	DR	CHK	DATE	REVISE ONLY ON CAD SYSTEM	SCALE	—	—	—	—	—	—	—	—	—	—	—	—	—
EDP NO.																			
ENG. NO.																			
TITLE 名称	モレックス 日本モロックス株式会社																		
3.5 WIRE TO BOARD CONN.																			
WAFFER ASS'Y (ST.)																			

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